L Number	Hits	Search Text	DB	Time stamp
1	415	257/706 and (laser or "LED" or light near	USPAT;	2004/04/30 23:15
_		emit\$3)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	1
			IBM TDB	
2	481	257/433 and (laser or "LED" or light near	USPAT;	2004/04/30 23:20
		emit\$3)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	ĺ
		055 (505	IBM_TDB	
3	301	257/707 and (laser or "LED" or light near	USPAT;	2004/04/30 23:24
		emit\$3)	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
4	253	(257/712 or 257/713 or 257/714) and (laser	USPAT;	2004/04/30 23:31
] -	255	or "LED" or light near emit\$3) same heat	US-PGPUB;	2004,04,30 23.31
		with (sink or slug or plate or plane or	EPO; JPO;	
		spreader or stiffener or transfer or	DERWENT;	· 1
		dissipat43)	IBM TDB	1
5	101	(257/715 or 257/716 or 257/717) and (laser	USPAT;	2004/04/30 23:31
		or "LED" or light near emit\$3) same heat	US-PGPUB;	
[with (sink or slug or plate or plane or	EPO; JPO;	
		spreader or stiffener or transfer or	DERWENT;	
		dissipat43)	IBM_TDB	
6	139	(257/718 or 257/719 or 257/720 or 257/721)	USPAT;	2004/04/30 23:34
		and (laser or "LED" or light near emit\$3)	US-PGPUB;	
		same heat with (sink or slug or plate or	EPO; JPO;	
		plane or spreader or stiffener or transfer	DERWENT;	
7	920	or dissipat43) (385/88 or 438/122 or 372/36) and (laser	IBM_TDB USPAT;	2004/04/30 23:47
7	320	or "LED" or light near emit\$3) same heat	US-PGPUB;	2004/04/30 23.4/
		with (sink or slug or plate or plane or	EPO; JPO;	
		spreader or stiffener or transfer or	DERWENT;	
		dissipat43)	IBM TDB	
8	1052	(semiconductor or die or chip or IC) and	USPAT;	2004/04/30 23:49
		(laser or "LED" or light near emit\$3) same	US-PGPUB;	
		heat with (sink or slug or plate or plane	EPO; JPO;	
		or spreader or stiffener or transfer or	DERWENT;	
		dissipat43) with (double or dual or both	IBM_TDB	
	000	or multi\$4 or second)	HODAM.	2004/04/30 23:50
9	839	((semiconductor or die or chip or IC) and	USPAT; US-PGPUB;	2004/04/30 23:30
		(laser or "LED" or light near emit\$3) same heat with (sink or slug or plate or plane	EPO; JPO;	
		or spreader or stiffener or transfer or	DERWENT;	1
		dissipat43) with (double or dual or both	IBM_TDB	
		or multi\$4 or second)) not ((385/88 or		
		438/122 or 372/36) and (laser or "LED" or		
		light near emit\$3) same heat with (sink or		
		slug or plate or plane or spreader or		
		stiffener or transfer or dissipat43))		
10	804	((semiconductor or die or chip or IC) and	USPAT;	2004/04/30 23:50
		(laser or "LED" or light near emit\$3) same	US-PGPUB;	
		heat with (sink or slug or plate or plane	EPO; JPO;	
		or spreader or stiffener or transfer or	DERWENT;	
		dissipat43) with (double or dual or both	IBM_TDB	
		or multi\$4 or second)) not (((385/88 or 438/122 or 372/36) and (laser or "LED" or	1	
		light near emit\$3) same heat with (sink or	1	
		slug or plate or plane or spreader or]
		stiffener or transfer or dissipat43)) or		
		(257/706 and (laser or "LED" or light near		
		emit\$3)) or (257/433 and (laser or "LED"		
		or light near emit\$3)) or (257/707 and		
		(laser or "LED" or light near emit\$3)) or		
]		((257/712 or 257/713 or 257/714) and]
]		(laser or "LED" or light near emit\$3) same	[1
		heat with (sink or slug or plate or plane		
1		or spreader or stiffener or transfer or	1	
_		dissipat43))) 5454002.pn./	USPAT	2004/04/28 03:48
	<u> </u>	Jajayova.pii./	1 00121	2004/04/20 03:40

-	1	5454002.pn. and isolat\$3 with attach\$3	USPAT	2004/04/28 04:12
-	1	(light near emitting near device) and	USPAT	2004/04/28 04:38
		adhesive with solder with heat near sink		
-	0	, ,,,,,,,,	USPAT	2004/04/28 04:38
		adhesive with solder with heat near sink		
		with second near heat		
-	0	(== 3000	USPAT	2004/04/28 04:38
		adhesive with heat near sink with second		
		near heat		
_	0	(light near emitting near device or laser	USPAT	2004/04/28 04:39
		or LED) and adhesive with solder with heat		
		near sink with second near heat		
-	6	(light near emitting near device or laser	USPAT ·	2004/04/28 04:43
		or LED) and adhesive with heat near sink		
		with second near heat		
_	0	(light near emitting near device or laser	USPAT	2004/04/28 04:44
		or LED) and adhesive with heat near sink		
		with heat near stiffener		
. –	6	(light near emitting near device or laser	USPAT	2004/04/28 04:46
		or LED) and adhesive with heat near sink		
		with stiffener		
 	337		USPAT	2004/04/28 04:49
		or LED) and adhesive with heat near sink		
		with heat		
-	81		USPAT	2004/04/28 04:52
		or LED) and adhesive with heat near sink		1
		with heat) and adhesive with heat near		
		sink with heat and adhesive with solder		l
-	3	((light near emitting near device or laser	USPAT	2004/04/28 04:52
		or LED) and adhesive with heat near sink		
		with heat) and adhesive with heat near		
		sink with heat and adhesive with solder		1
		and ("AuGe" or "PbSn")		